

II. LISTING OF THE CLAIMS:

The present claims will replace all prior versions of claims in the present application.

1. (Previously Presented) A thermosetting resin composition comprising:

(1) a metal salt of a disubstituted phosphinic acid, and

(2) a resin having a dielectric constant of 2.9 or less at a frequency of 1 GHz or more.

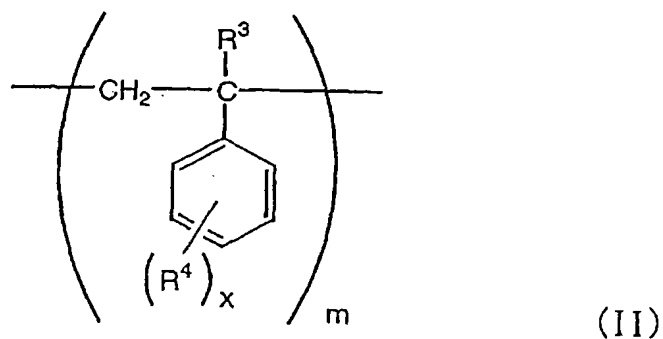
2. (Previously Presented) The thermosetting resin composition according to claim 1, wherein the dielectric constant of the thermosetting resin composition is 3.0 or less at a frequency of 1 GHz or more.

3. (Previously Presented) The thermosetting resin composition according to claim 1, which further comprises (3) a thermosetting nitrogen atom-containing resin.

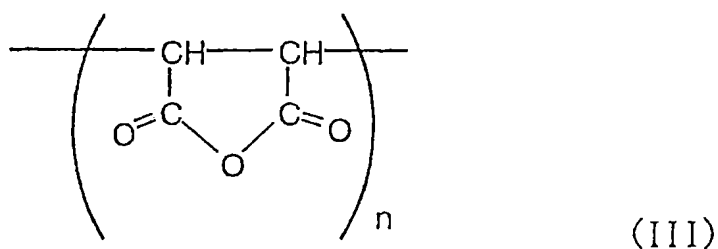
4. (Previously Presented) The thermosetting resin composition according to claim 1, wherein the component (2) is at least one resin compositions selected from the group consisting of:

copolymer resin (2-1) comprising:

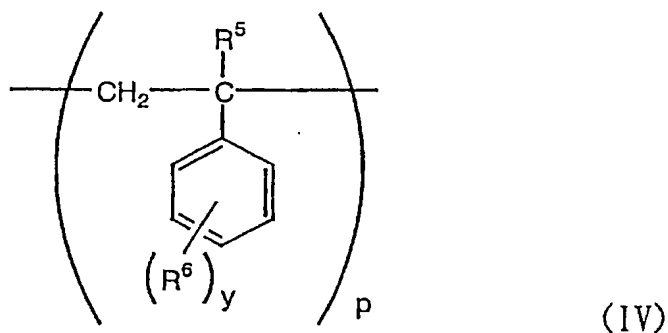
monomer unit (a) represented by formula (II):



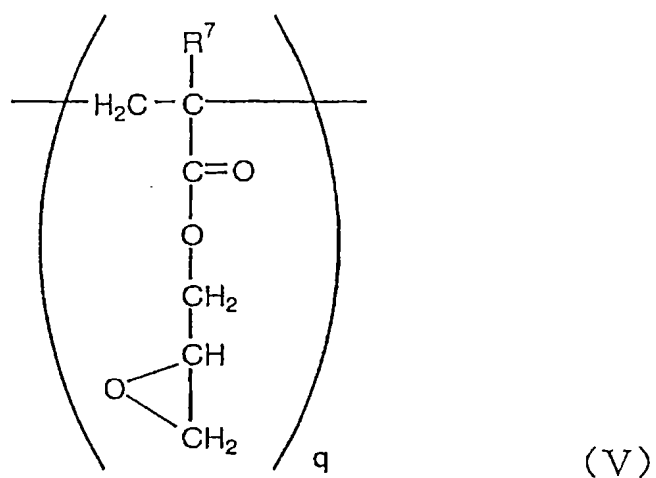
wherein R^3 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^4 's are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; x is an integer of 0 to 3; and m is a natural number representing the repeating number of a monomer unit in a copolymer, and monomer unit (b) represented by formula (III):



wherein n is a natural number representing the repeating number of a monomer unit in a copolymer;
copolymer resin (2-2) comprising:
monomer unit (c) represented by formula (IV):

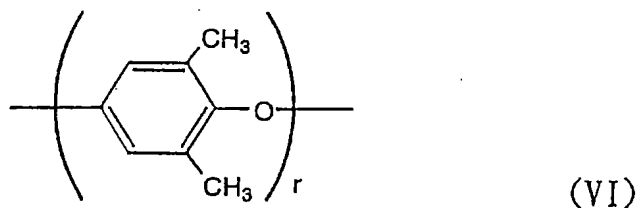


wherein R^5 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^6 s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; y is an integer of 0 to 3; and p is a natural number representing the repeating number of a monomer unit in a copolymer, and monomer unit (d) represented by formula (V):



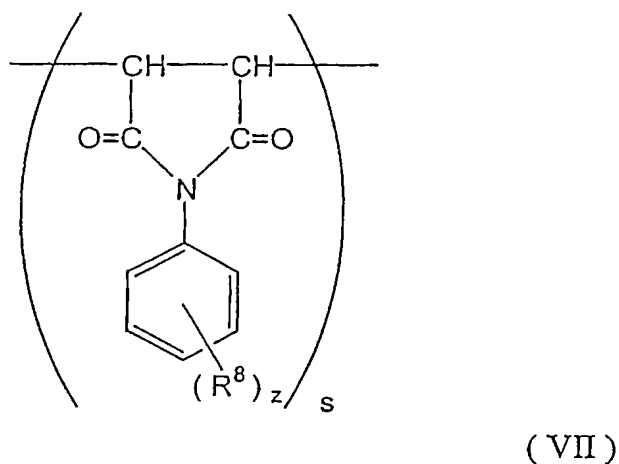
wherein R^7 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; and q is a natural number representing the repeating number of a monomer unit in a copolymer; and resin (2-3) comprising:

monomer unit (e) represented by formula (VI):



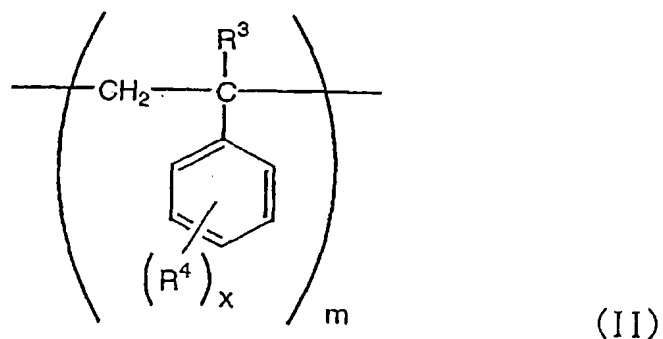
wherein r is a natural number representing the repeating number of a monomer unit in a copolymer.

5. (Previously Presented) The thermosetting resin composition according to claim 4, wherein the copolymer resin (2-1) is a copolymer resin further comprising:
monomer unit (f) represented by the following formula (VII):

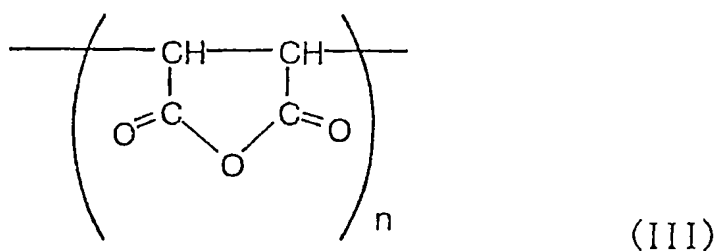


wherein R^8 is a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group, a hydroxyl group, a thiol group or a carboxyl group; z is an integer of 0 to 3; and s is a natural number representing the repeating number of a monomer unit in a copolymer.

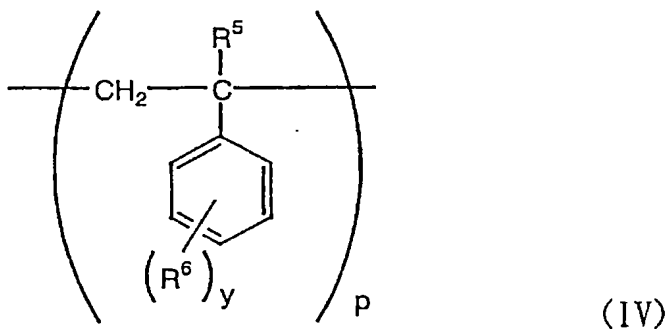
6. (Previously Presented) The thermosetting resin composition according to claim 1, which further comprises (4) an epoxy resin.
7. (Previously Presented) A prepreg using the thermosetting resin composition according to claim 1.
8. (Previously Presented) A laminated board obtained by using and laminate molding the prepreg according to claim 7.
9. (Previously Presented) A thermosetting resin composition comprising a metal salt of a disubstituted phosphinic acid, wherein a dielectric constant of the composition is 3.0 or less at a frequency of 1 GHz or more.
10. (Previously Presented) The thermosetting resin composition according to claim 2, which further comprises (3) a thermosetting nitrogen atom-containing resin.
11. (Previously Presented) The thermosetting resin composition according to claim 2, wherein the component (2) is at least one resin compositions selected from the group consisting of:
copolymer resin (2-1) comprising:
monomer unit (a) represented by formula (II):



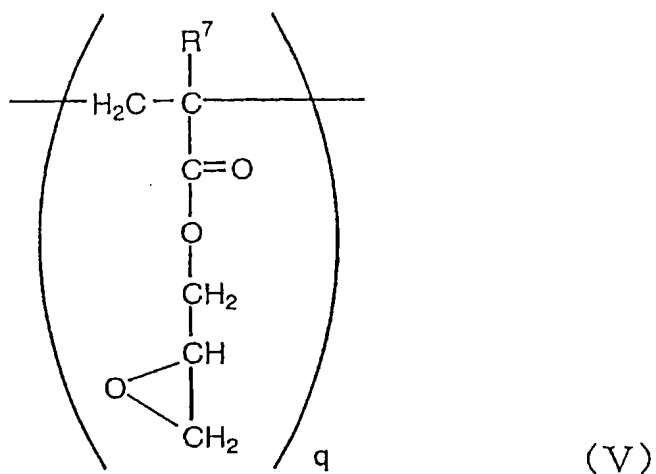
wherein R^3 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^4 's are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; x is an integer of 0 to 3; and m is a natural number representing the repeating number of a monomer unit in a copolymer, and monomer unit (b) represented by formula (III):



wherein n is a natural number representing the repeating number of a monomer unit in a copolymer;
copolymer resin (2-2) comprising:
monomer unit (c) represented by formula (IV):

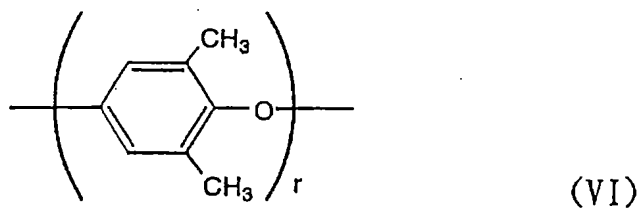


wherein R^5 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R^6 s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; y is an integer of 0 to 3; and p is a natural number and representing the repeating number of a monomer unit in a copolymer, and monomer unit (d) represented by formula (V):



wherein R^7 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; and q is a natural number representing the repeating number of a monomer unit in a copolymer; and resin (2-3) comprising:

monomer unit (e) represented by formula (VI):



wherein r is a natural number representing the repeating number of a monomer unit in a copolymer.

12. (Previously Presented) The thermosetting resin composition according to claim 2, which further comprises (4) an epoxy resin.